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Quarterly Reliability Monitoring Results

Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier		User Part Number												
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		PESD3V3S4UD-Q Part Description												
								Nexperia DHAM Protection SMD package Test Conditions Duration # Lots # Quantity # Rejects						
			TEST											
			Pre- and Post-Stress											
		# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below						
		JESD22-A113 Bake Tamb = 125 °C	24 hours											
	PC	Soak Tamb = $85 ^{\circ}$ C, RH = 85%	168 hours											
# A1	Preconditioning	Reflow soldering	3 cycles	438	24630	0								
		MIL-STD-750-1												
	HTRB	M1038 Method A												
		Tj = Tjmax, $Vr = 100%$ of max. datasheet												
# B1	Bias	reverse voltage	1000 hours	166	10040	0								
	тс	JESD22-A104												
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	131	7760	0								
π Ατ	· · · · · · · · · · · · · · · · · · ·		1000 cycles	151	//00	0								
	UHAST	JESD22-A118												
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	– 96 hours	131	7760	0								
		JESD22-A102	96 Hours											
	AC	Tamb = 121 °C, RH = 100 %												
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)												
		150000 4141												
	H3TRB	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of												
# 42 alt	High Humidity High Temperature Reverse Bias		1000 hours	101	7760	0								
# A2 alt	Temperature Reverse blas	MIL-STD-750 Method 1037	1000 hours	131	7760	0								
	IOL	ton = toff, devices powered to insure ΔT_i =												
# A5	Intermittent Operating Life		1000 hours	n.a.	n.a.	n.a.								
		· .												
	RSH	JESD22-A111												
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	45	1350	0								
	SD													
# C10	Solderability	J-STD-002		111	1110	0								

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Protection	10040	0	0,42	2,36E+09

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